

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A wiring board comprising:
a conductor layer comprising Fe and Cu; and
at least one of a radiator, a connection terminal, a cover and a circuit component,
connected to the conductor layer through a joining member,
which is wiring board obtained by coating a copper paste comprising a copper powder, an organic vehicle and an Fe₂O₃ particle as a conductor layer on a ceramic green sheet, and simultaneously firing the ceramic green sheet and coated copper paste.
2. (original): The wiring board according to claim 1, wherein a surface of the conductor layer is subjected to a plating treatment.
3. (canceled)
4. (currently amended): The wiring board according to ~~claim 3~~ claim 1, wherein the copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.
5. (currently amended): The wiring board according to ~~claim 3~~ claim 1, wherein the copper paste comprises a ceramic particle having an average particle size of 100 nm or less.
6. (currently amended): The wiring board according to ~~claim 3~~ claim 1, which is obtained by a method comprising the steps of

coating the copper paste on a ceramic green sheet;
exposing the coated sheet to a wet nitrogen atmosphere at 650 to 900°C so as to remove
organic components; and

simultaneously firing the ceramic green sheet and coated copper paste sheet at 850 to
1,050°C after the exposing.

7. (original): A copper paste comprising a copper powder, an organic vehicle and an
 Fe_2O_3 particle.

8. (original): The copper paste according to claim 7, wherein the copper paste
comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper
powder.

9. (original): The copper paste according to claim 7, which comprises a ceramic
particle having an average particle size of 100 nm or less.